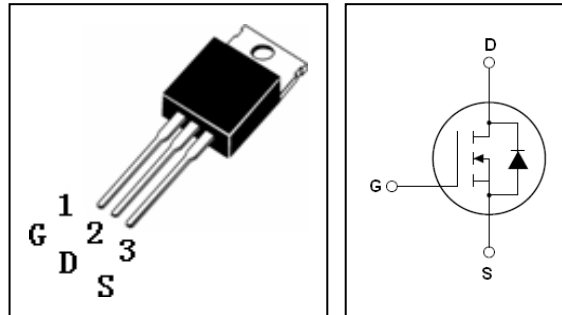


### Main Product Characteristics

$V_{DSS}$	100V (Typ)
$R_{DS(on)}$	6m $\Omega$ (Typ)
$I_D$	130A



SSF1007 Top View (TO-220)

### Features and Benefits

- Advanced trench MOSFET process technology
- Ideal for convertors and power controls
- Ultra low on-resistance
- 150°C operating temperature
- High Avalanche capability and 100% tested

### Description

The SSF1007 utilizes the latest processing techniques to achieve high cell density, low on-resistance and high repetitive avalanche rating. These features make this device extremely efficient and reliable device for use in power switching applications and a wide variety of other applications.

### Absolute Max Ratings

Symbol	Parameter	Max.	Units
$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ ①	130	A
$I_D @ T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ ①	91	
$I_{DM}$	Pulsed Drain Current②	520	
$I_{SM}$	Pulsed Source Current.(Body Diode)	520	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation③	258	W
	Linear derating factor	1.7	W/°C
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulse Avalanche Energy @ $L=0.3\text{mH}$ ②	735	mJ
$I_{AR}$	Avalanche Current @ $L=0.3\text{mH}$ ②	75	A
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +175	°C

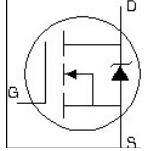
### Thermal Resistance

Symbol	Characteristics	Value	Unit
$R_{\theta JC}$	Junction-to-Case③	0.58	°C/W
$R_{\theta JA}$	Junction-to-Ambient ( $t \leq 10\text{s}$ ) ④	62	°C/W

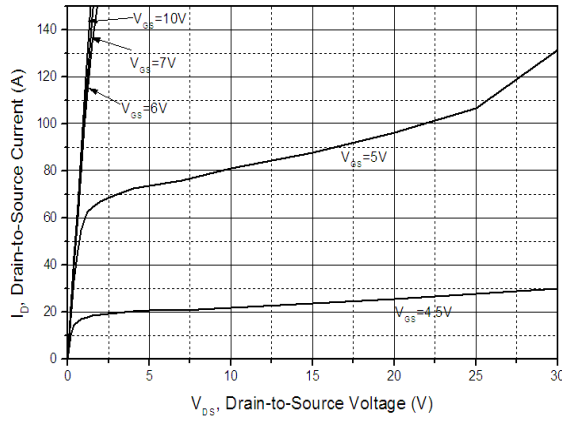
**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max	Units	Conditions
$BV_{DSS}$	Drain-to-Source Breakdown Voltage	100	—	—	V	$V_{GS} = 0V$ , $I_D = 250\mu A$
$R_{DS(on)}$	Static Drain-to-Source On-resistance	—	5	6	m $\Omega$	$V_{GS} = 10V$ , $I_D = 75A$ ③
$V_{GS(th)}$	Gate Threshold Voltage	2	—	4	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
$I_{DSS}$	Drain-to-Source Leakage Current	—	—	20	$\mu A$	$V_{DS} = 100V$ , $V_{GS} = 0V$
		—	—	250		$V_{DS} = 80V$ , $V_{GS} = 0V$ , $T_J = 125^\circ\text{C}$
$I_{GSS}$	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -20V$
$Q_g$	Total Gate Charge	—	243	170	nC	$I_D = 75A$ $V_{DS} = 50V$ $V_{GS} = 10V$ ③
$Q_{gs}$	Gate-to-Source Charge	—	47	—		
$Q_{gd}$	Gate-to-Drain ("Miller" Charge)	—	92	—		
$t_{d(on)}$	Turn-on Delay Time	—	28	—	ns	$V_{DD} = 65V$ $I_D = 75A$ $R_G = 2.7 \Omega$ $V_{GS} = 10V$ ③
$t_r$	Rise Time	—	108	—		
$t_{d(off)}$	Turn-Off Delay Time	—	123	—		
$t_f$	Fall Time	—	120	—		
$C_{iss}$	Input Capacitance	—	8456	—	pF	$V_{GS} = 0V$ $V_{DS} = 50V$ $f = 500\text{KHz}$
$C_{oss}$	Output Capacitance	—	454	—		
$C_{rss}$	Reverse Transfer Capacitance	—	417	—		

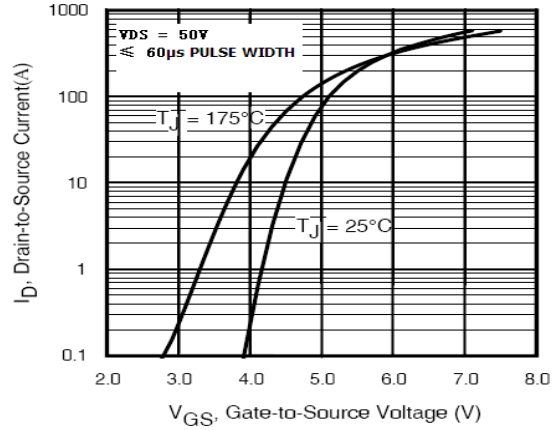
**Source-Drain Ratings and Characteristics**

	Parameter	Min.	Typ.	Max	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	130	A	MOSFET symbol showing the integral reverse p-n junction diode. 
$I_{SM}$	Pulsed Source Current (Body Diode) ①	—	—	520		$T_J = 25^\circ\text{C}$ , $I_S = 75A$ , $V_{GS} = 0V$ ③
$V_{SD}$	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}$ , $I_F = 75A$ , $V_{DD} = 20V$ $di/dt = 100A/\mu s$ ③
$t_{rr}$	Reverse Recovery Time	—	57	70	ns	$T_J = 25^\circ\text{C}$ , $I_F = 75A$ , $V_{GS}=0V$ $di/dt = 100A/\mu s$ ③
$Q_{rr}$	Reverse Recovery Charge	—	156	170	nC	
$t_{on}$	Forward Turn-on Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S+L_D$ )				

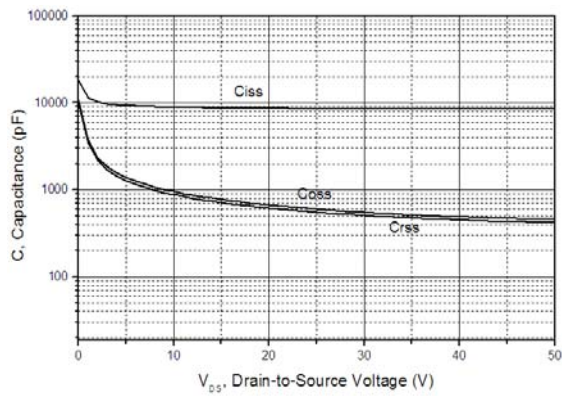
**Typical Electrical and Thermal Characteristics**



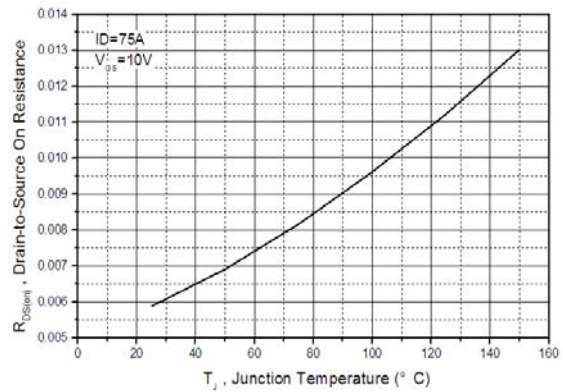
**Figure 1. Typical Output Characteristics**



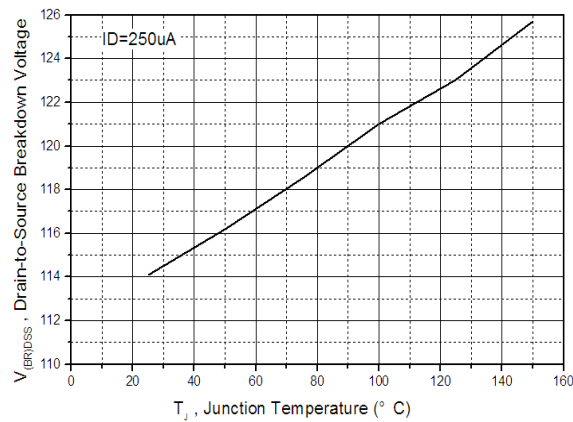
**Figure 2. Typical Transfer Characteristics**



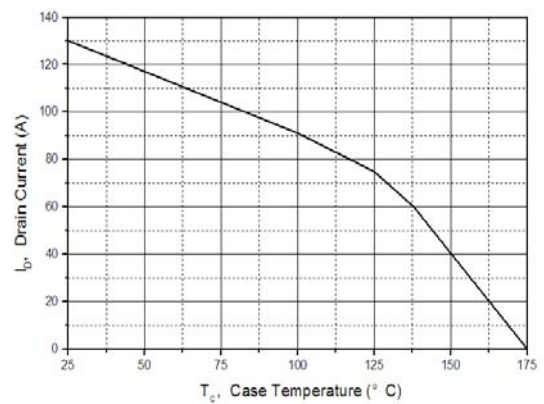
**Figure 3. Typical Capacitance Vs. Drain-to-Source Voltage**



**Figure 4. Normalized On-Resistance Vs. Case Temperature**

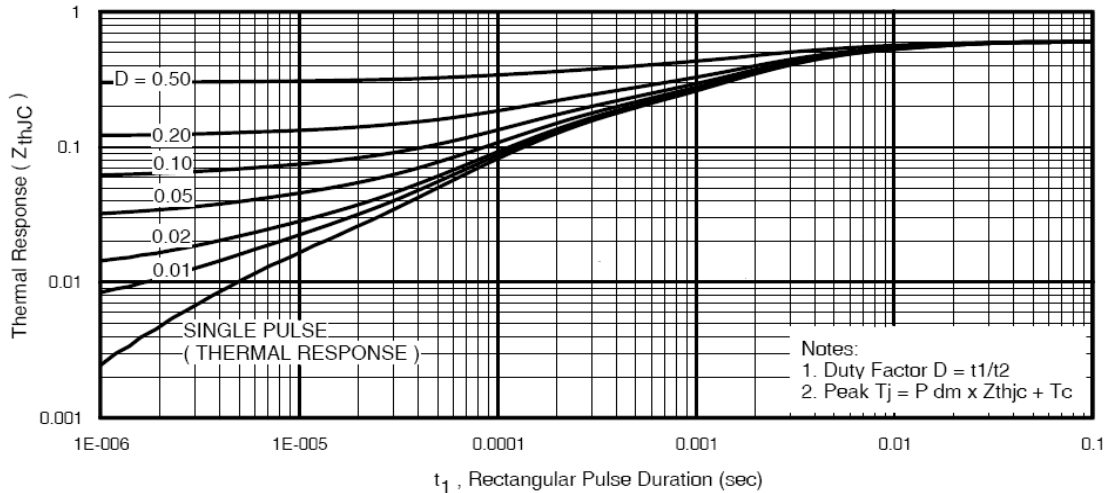


**Figure 5. Drain-to-Source Breakdown Voltage vs. Temperature**



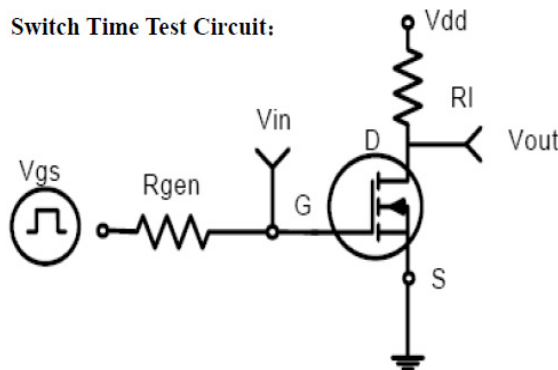
**Figure 6. Maximum Drain Current Vs. Case Temperature**

### Typical Electrical and Thermal Characteristics

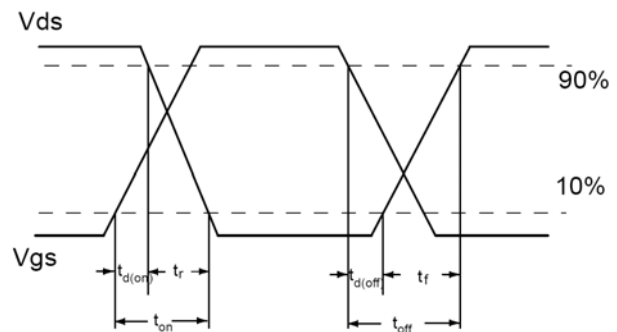


**Figure 7. Maximum Effective Transient Thermal Impedance, Junction-to-Case**

Switch Time Test Circuit:



Switching Waveforms

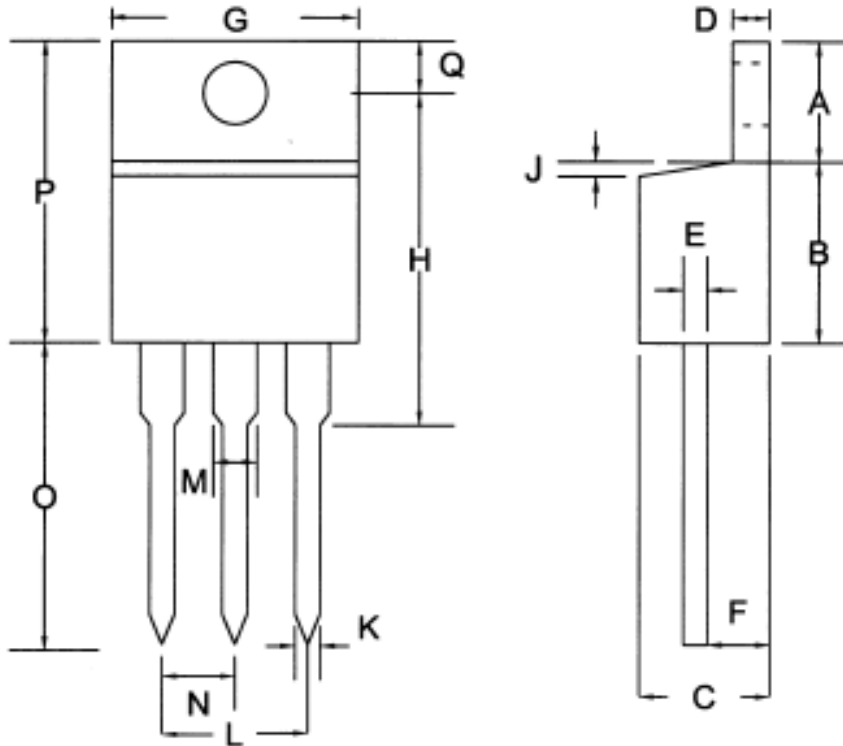


### Notes

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by  $T_{jmax}$ , starting  $T_j = 25^\circ C$ ,  $L = 0.3mH$   $R_G = 50\Omega$ ,  $I_{AS} = 70A$ ,  $V_{GS} = 10V$ . Part not recommended for use above this value.
- ③ Pulse width < 1.0ms; duty cycle < 2%.
- ④ This is only applied to TO-220 package

**Mechanical Data**

TO-220



Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min	Nom	Max	Min	Nom	Max
A	5.58	6.54	7.49	0.220	0.257	0.295
B	8.38	8.64	8.90	0.330	0.340	0.350
C	4.07	4.45	4.82	0.160	0.175	0.190
D	1.15	1.27	1.39	0.045	0.050	0.055
E	0.35	0.45	0.60	0.014	0.018	0.024
F	2.04	2.42	2.79	0.080	0.095	0.110
G	9.66	9.97	10.28	0.380	0.393	0.405
H	—	16.25	—	—	0.640	—
I	3.68	3.83	3.98	0.145	0.151	0.157
J	—	—	1.27	—	—	0.050
K	0.75	0.85	0.95	0.030	0.033	0.037
L	4.83	5.08	5.33	0.190	0.200	0.210
M	1.15	1.33	1.52	0.045	0.052	0.060
N	2.42	2.54	2.66	0.095	0.100	0.105
O	12.70	13.48	14.27	0.500	0.531	0.562
P	14.48	15.17	15.87	0.570	0.597	0.625
Q	2.54	2.79	3.04	0.100	0.110	0.120